

Project Objectives

Goal: Characterize Properties of M-S Contacts

- Determine Al/Si Ratio Across Deposition Methods
 - Measure with XPS and SIMS
- Characterize Physical Properties of the Films
 - Image Sintered Films, Relate to Al/Si Content
- Examine TLM and Diode Characteristics
 - Relate to Al/Si Content and Diode Dimensions

Motivation

- Previous work in the RIT SMFL found defects in Flash Evaporated AlSi Films post 450°C Sinter, hypothesized to be Junction Spiking due to a Silicon-starved deposition

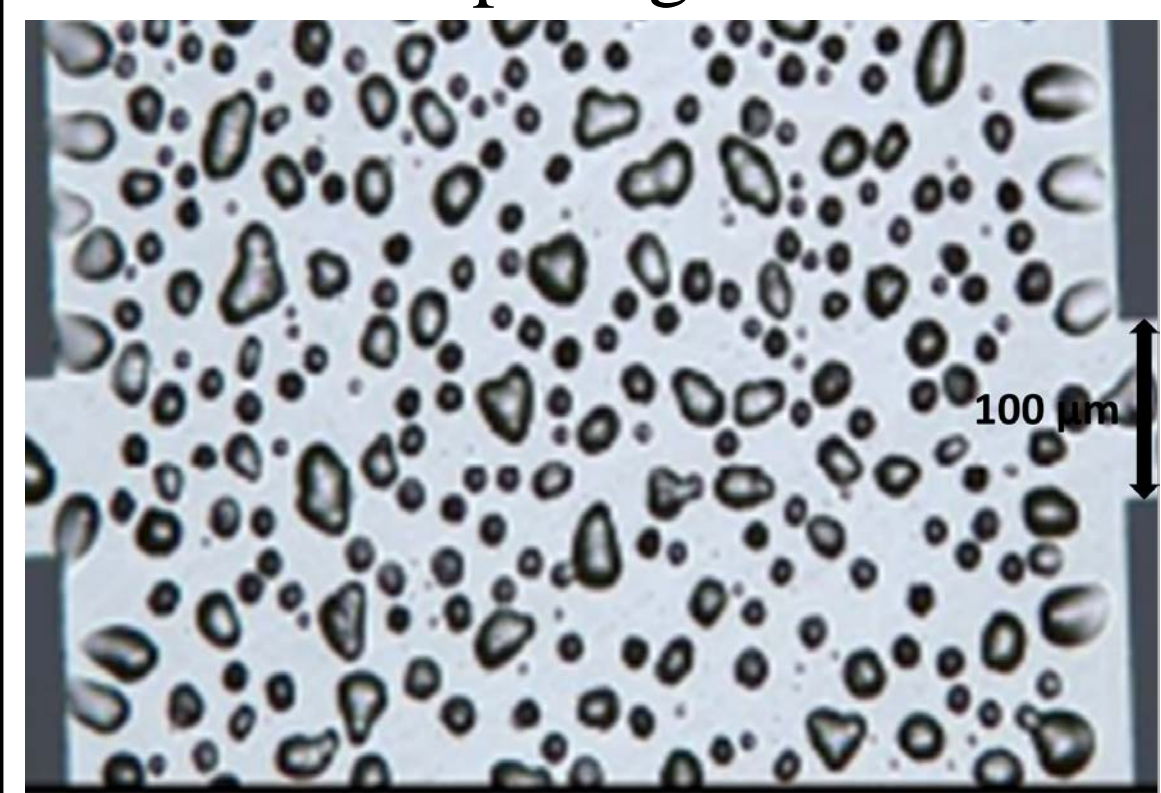


Fig 1. Defective AlSi Layer from Flash Evaporation[1]

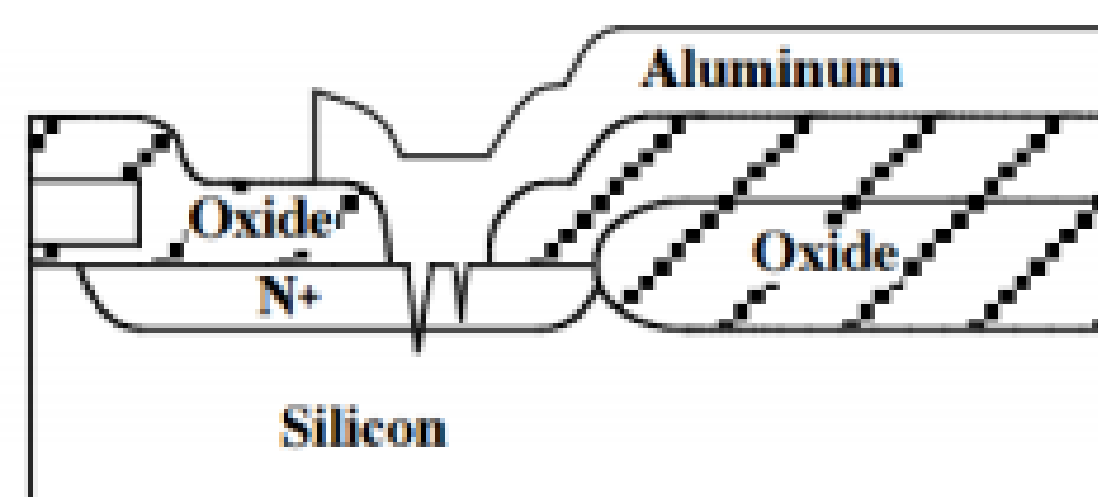


Fig 2. Cross Section of Junction Spiking[2]

- AlSi Films Deposited via the CVC601 DC Sputter system had a high resistivity, hypothesized to be due to a Silicon-rich deposition

Chemical Analysis of Al Depositions

- The AlSi Films will be Analyzed with X-ray Photoelectron Spectroscopy (XPS) and Secondary Ion Mass Spectrometry (SIMS)

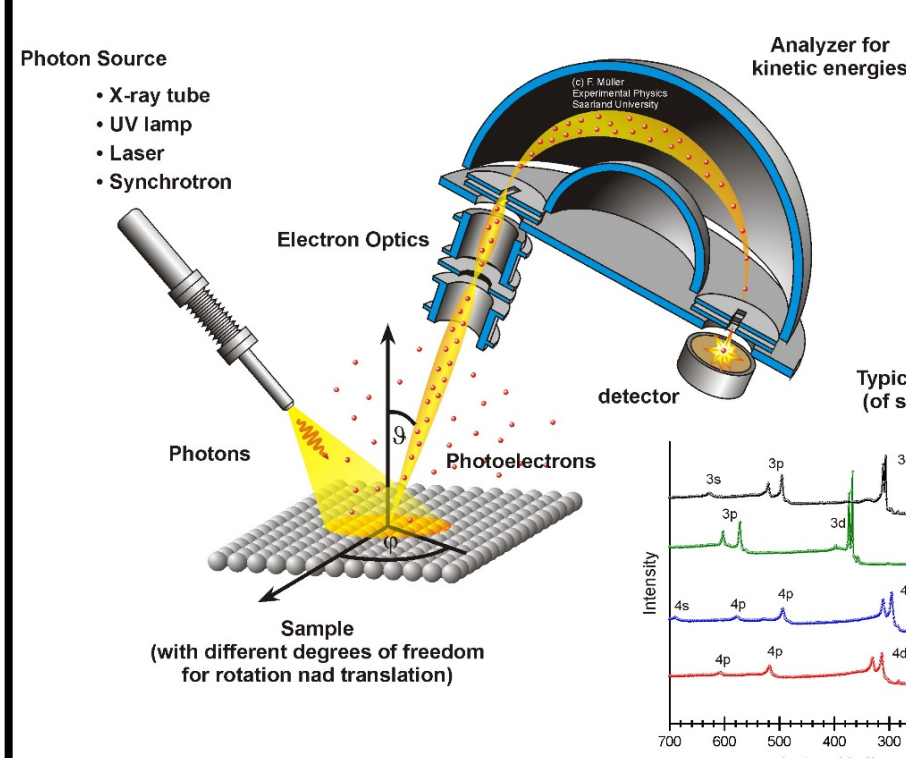


Fig 3. The General Operation and Output of XPS [3]

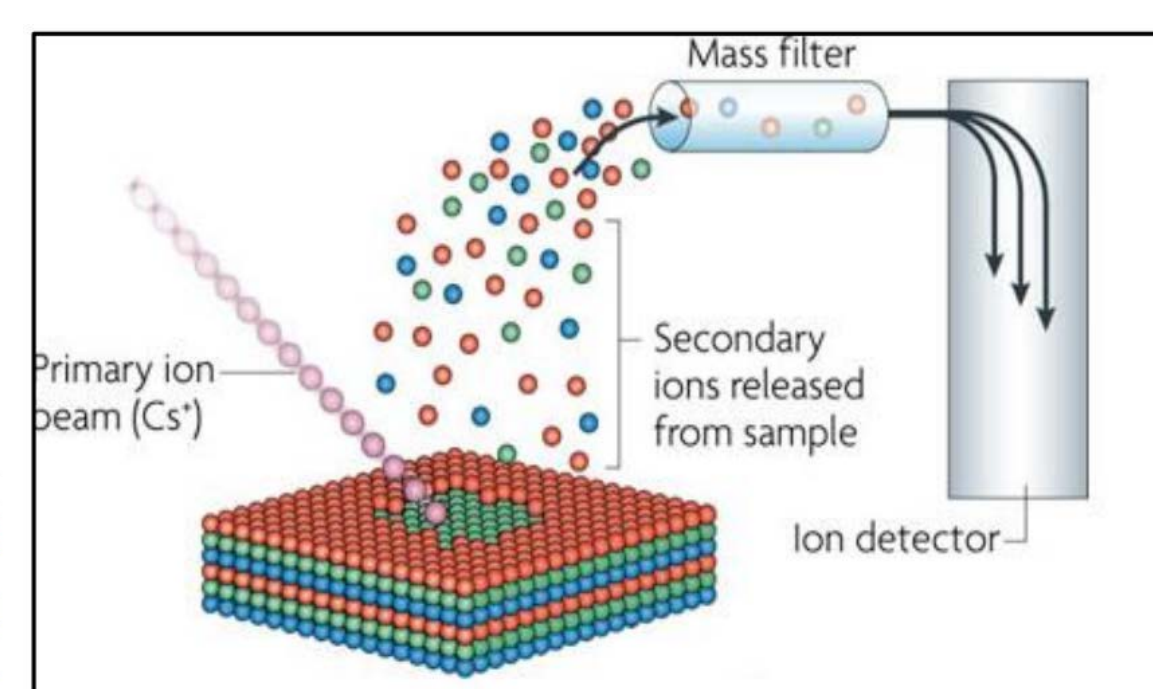


Fig 4. The General Operation of SIMS [4]

- These methods can provide the Al:Si ratios, the results of which can be related to the electrical and physical results of this study

XPS Results

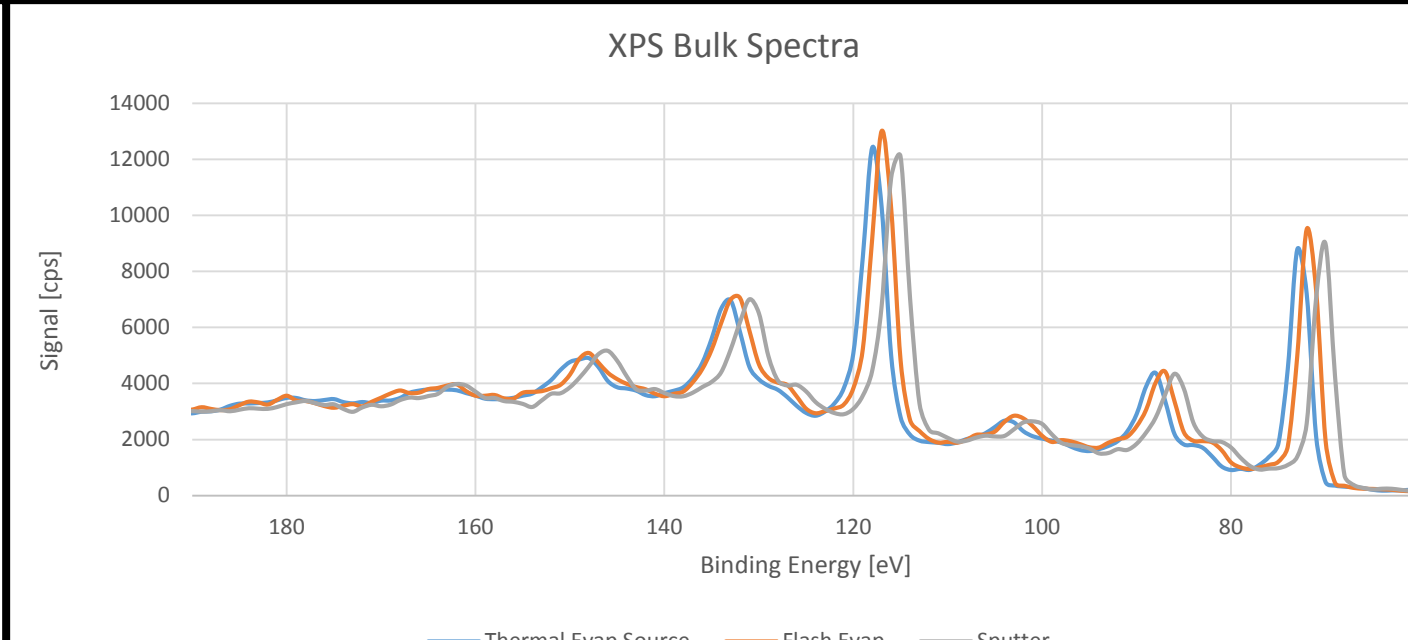


Fig. 5. Full Spectra of AlSi Films

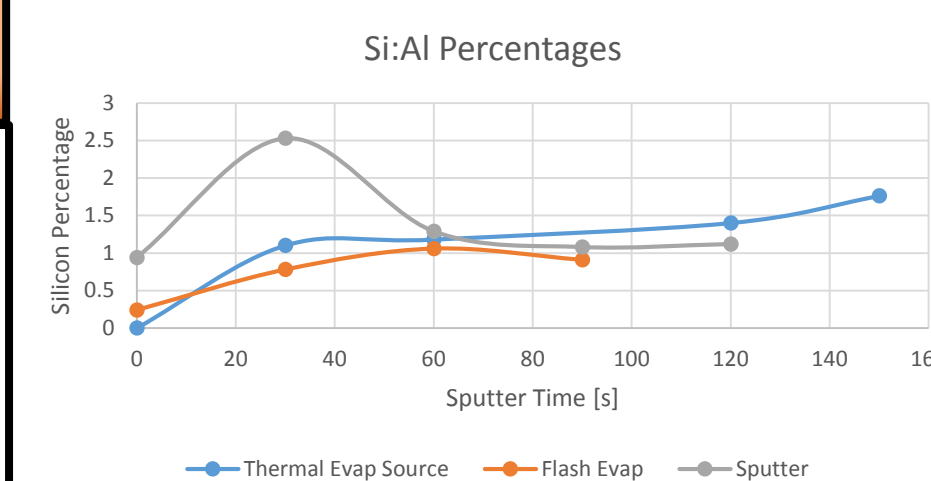


Fig. 6. Si Percentage vs FIB Sputter Time

Sample	Bulk %	Normalized Amount
Thermal Evap	1.29	1
Flash Evap	0.916	0.71
Sputter	1.1	0.85

Fig. 7. Normalized Bulk Si Percentage

- The Si Signal can be deconvolved from the Al Plasmon Peaks, but this introduces large error margins due to the sample's low Si content

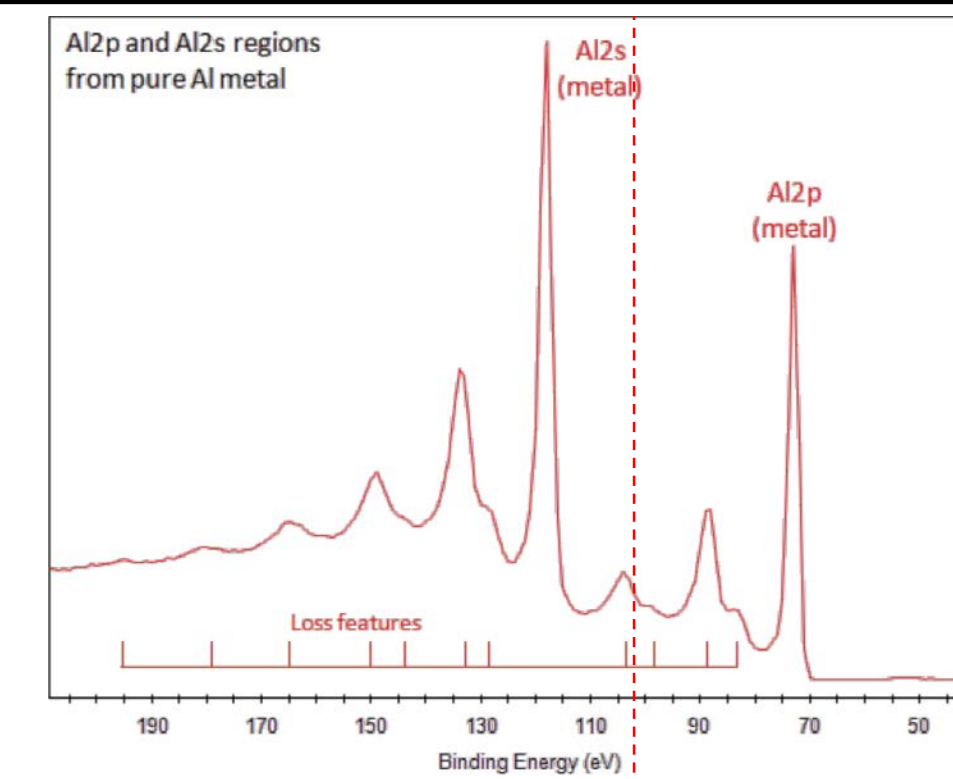


Fig. 8. Characteristic Al XPS Spectra [5]

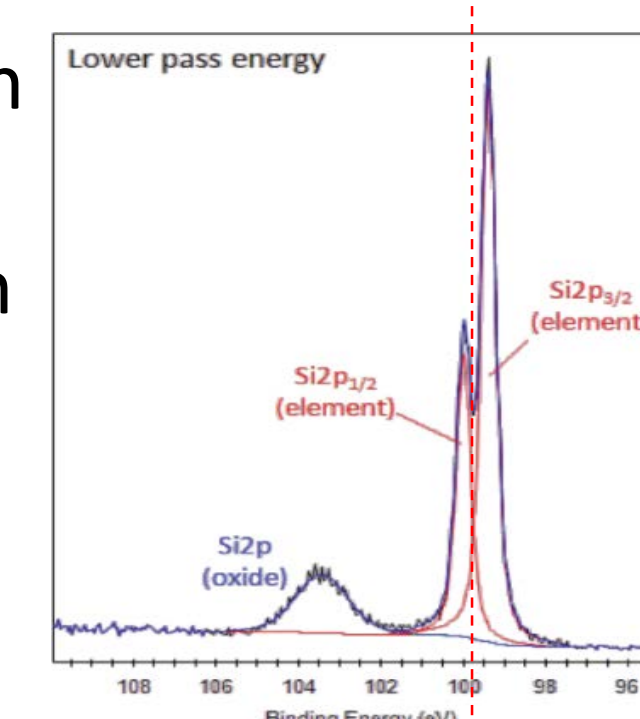


Fig. 9. Characteristic Si XPS Spectra [5]

Electrical Results

Transmission Line Measurements

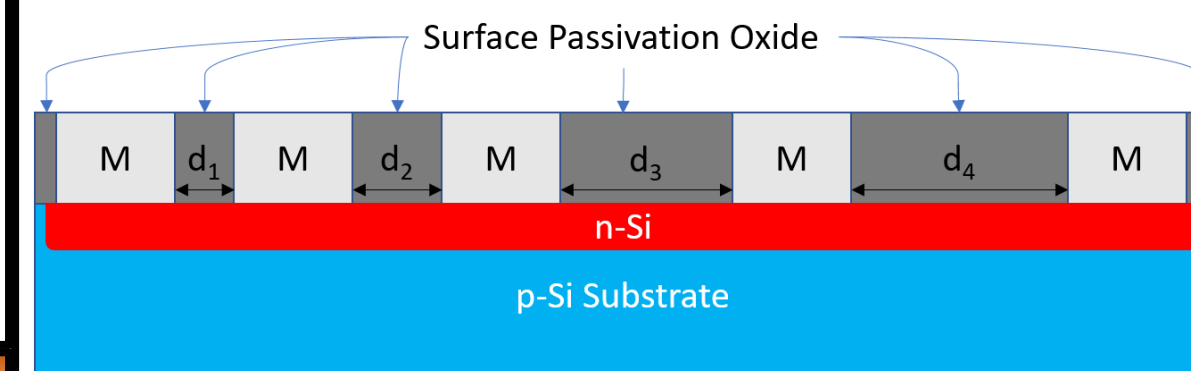


Fig. 10. TLM for Extracting Contact Resistance

- Due to Al to n-Si M-S contact and a low n-type contact doping, the contacts rectified

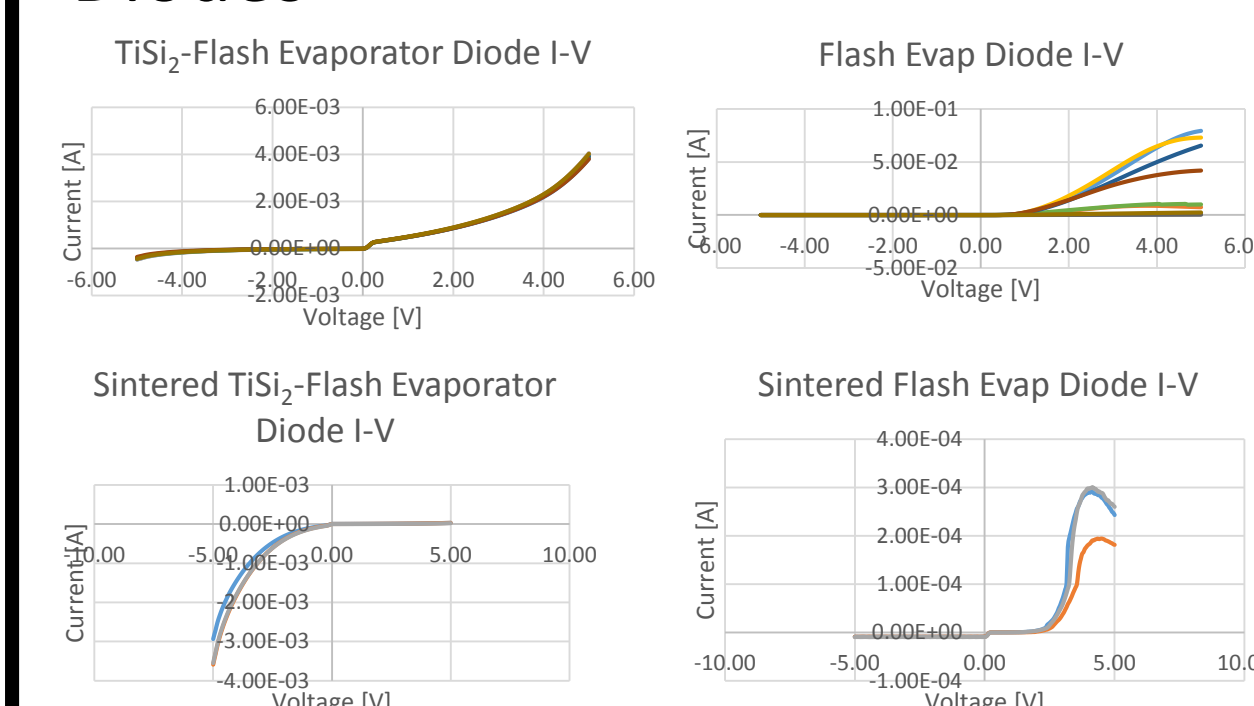


Fig. 12. Sinter's Varying Effects on Diode Characteristics

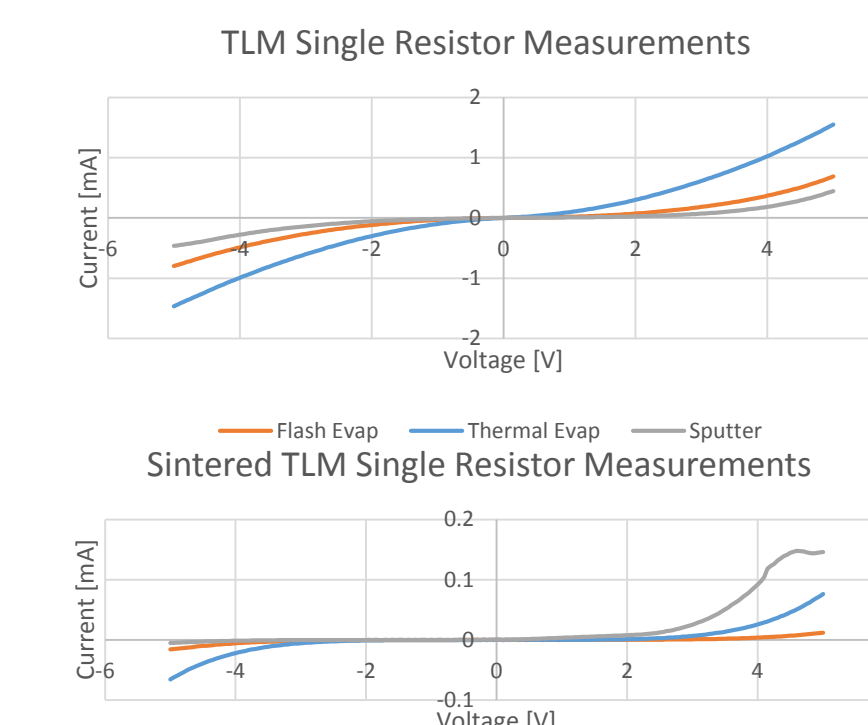


Fig. 11. Single Spacing TLM Rectifying Resistance Curves

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- Jenna Doran
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Physical Results

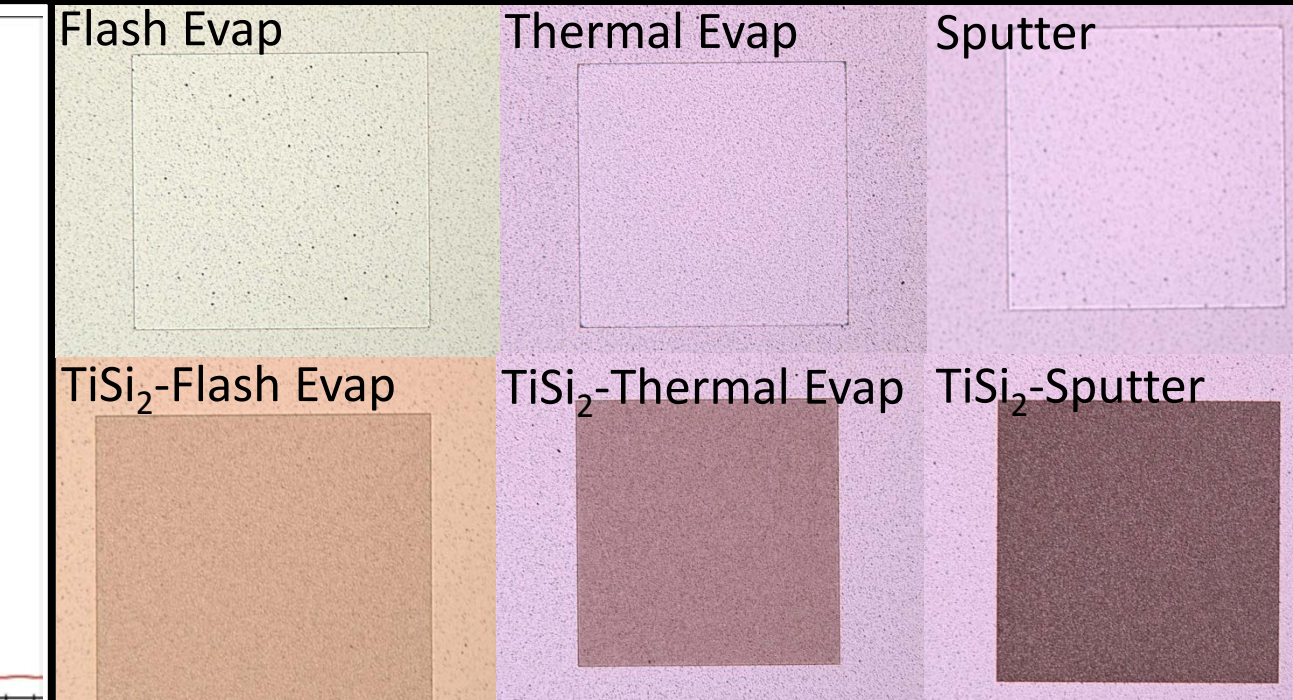


Fig. 13. 10x Microscope Images of Sintered Films

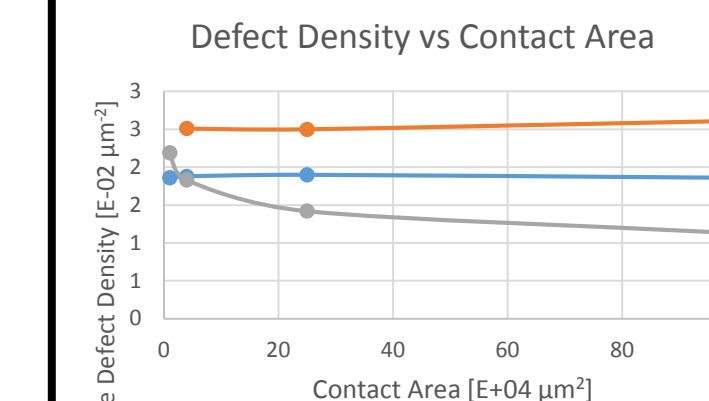


Fig. 14. Defect Density vs Contact Area

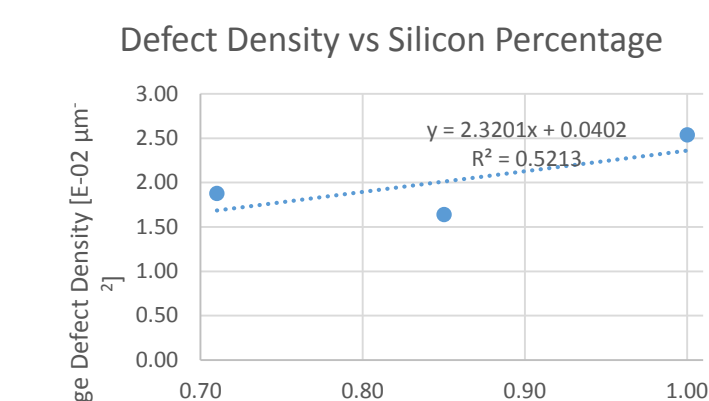


Fig. 15. Defect Density vs Si %

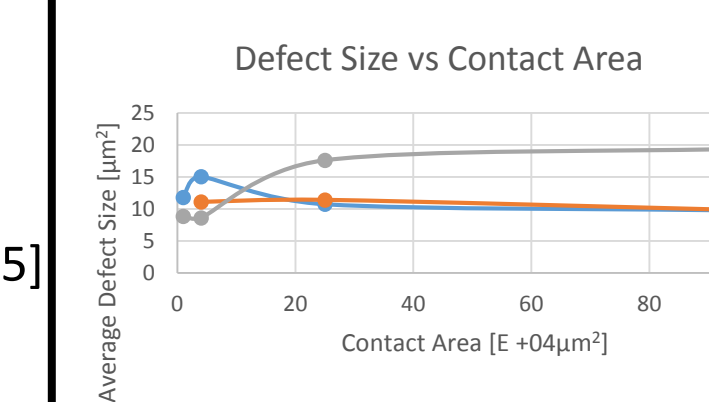


Fig. 16. Defect Size vs Contact Area

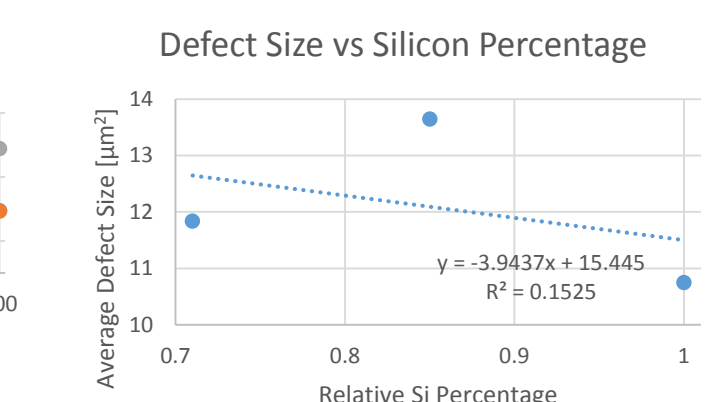


Fig. 17. Defect Size vs Si %

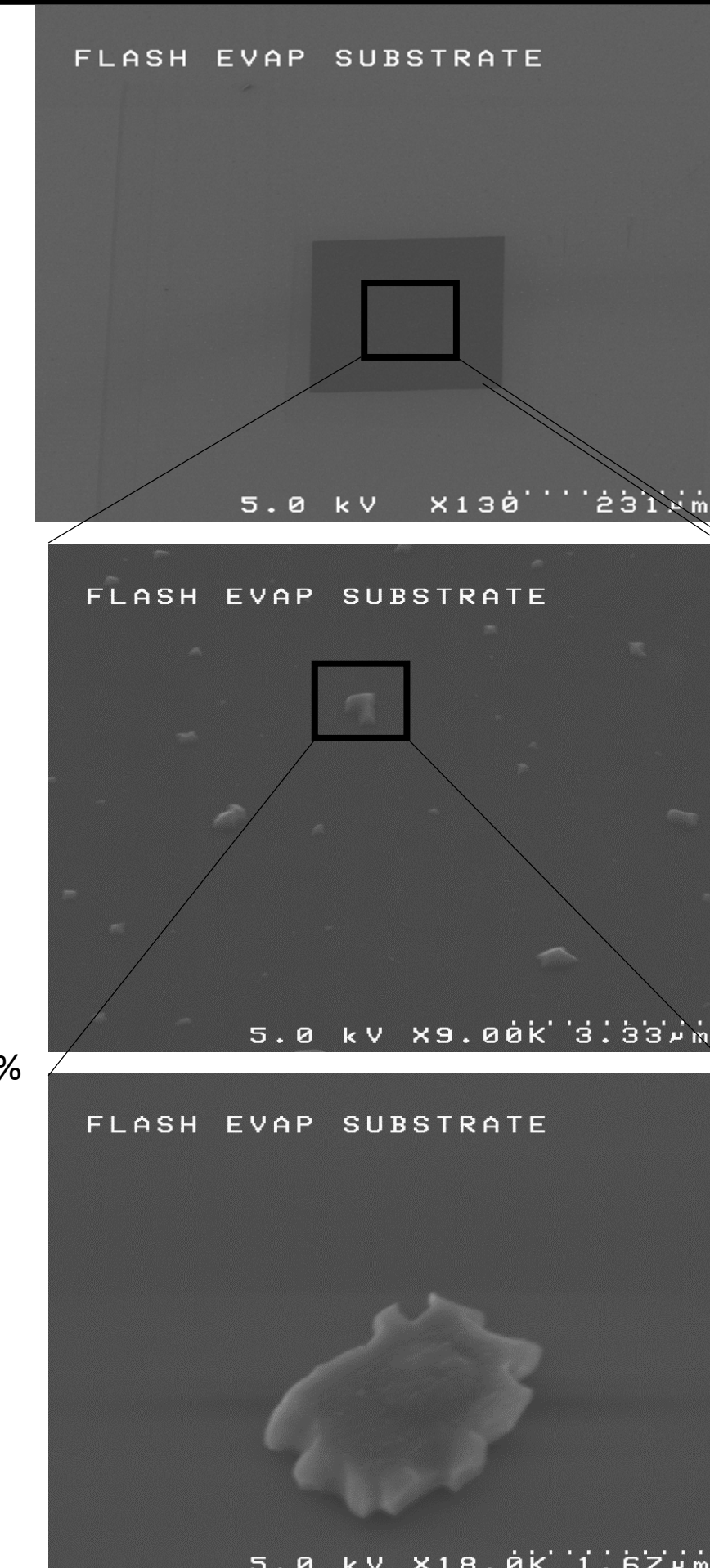


Fig. 18. SEM Images of Defects after Al Etch, Average Height of 1734Å

- The spotted film defect appears to match that of Figure 1
- This defect appeared in every film deposited after Sinter
- The defect manifested on every topology; over Si, over SiO₂, and over TiSi₂
- Upon Etching the Al, the roughness pattern remained
- The roughness presented itself as particles left on the surface, not pits from Junction Spiking

Conclusions

- The Defect Found in the Flash Evaporator is likely not Junction Spiking, but may be a function of the Silicon content in the deposited AlSi Film

Future Work

- Fabricate functional TLM structures to examine Contact Resistances of the films
- Use SIMS or Auger analysis to quantify the Silicon Content within the AlSi films
- Use EDS to determine the chemical makeup of the residue left on the Silicon

References

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- S. Grover, "Effect of Transmission Line Measurement (TLM) Geometry on Specific Contact Resistivity Determination," Master of Science, Materials Science, Rochester Institute of Technology, 2016.
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